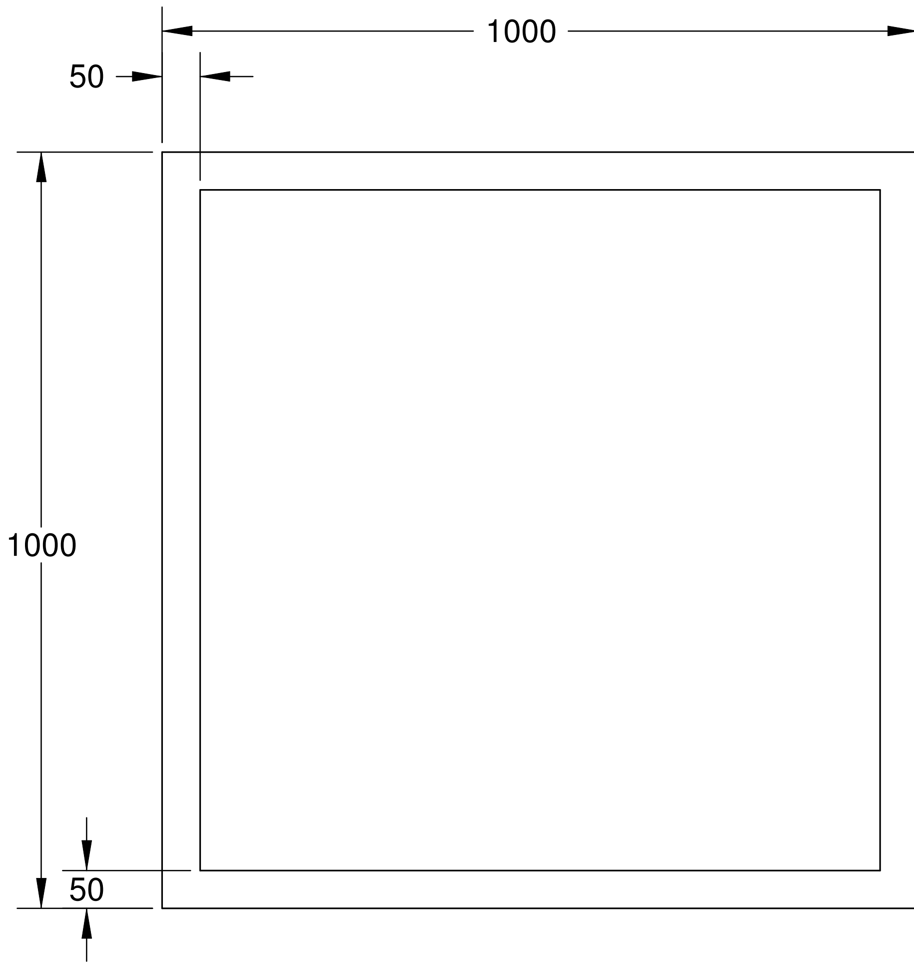
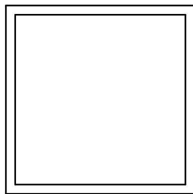
REVISIONS				
DATE	REV.	ECO	DESCRIPTION	APPROVED





SCALE 25:1

Notes: (Unless Otherwise Specified).
1) DIE MATERIAL IS SILICON.
2) DIE THICKNESS IS 250 um (10 MIL).
3) METALLIZATION 1.0 um ALUMINUM (Al) OVER 0.75 um SiO_2.
4) DIE IS WITHOUT PASSIVATION.
5) WIRE BONDABLE WITH GOLD (Au) OR ALUMINUM (Al) WIRE.
6) FULLY METALLIZED OVER ENTIRE SURFACE OF DIE.
7) TOLERANCE = ±1 um.

DIMENSIONS IN MICRONS
1000 um = 1. 0mm

PART NUMBER SYSTEM						
TD	-	1	-	1.0	-	BUS
SILICON TEST DIE		BOND PADS		DIE SIZE (mm)		FULLY METALLIZED

TOLERANCE UNLESS NOTED		
X.XX	+/-	0.01
X.XXX	+/-	0.005
X.XXXX	+/-	0.0005
ANGLES	+/-	0.5°
ALL DIMENSIONS IN ☒ INCHES ☐ MILLIMETERS		
THIRD ANGLE PROJECTION		

APPROVALS	DATE
DRAWN J. HINES	5/2/2010
ENG	
MFG	
QA	
CUST	
REVISED	

TopLine®

TITLE	Si TEST DIE TD SERIES		
SCALE 100:1	SIZE A	DRAWING NO. 151001	REV A
DO NOT SCALE DRAWING		SHEET 1 OF 1	